

SFM61-T7B Thru SFM68-T7B

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SFM61-T7B Thru SFM68-T7B

6.0A Surface Mount

Super Fast Rectifiers : 50 ~ 600V

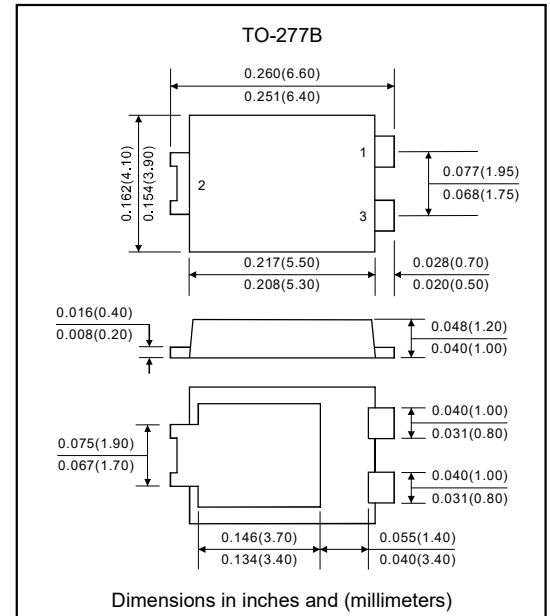
Features

- The plastic package carries Underwriters Laboratory Flammability Classification 94V-0.
- Idea for printed circuit board .
- Glass passivated junction chip .
- Low reverse leakage.
- High forward surge current capability.
- High temperature soldering guaranteed.
- Lead free parts, RoHS requirements.
- Suffix "-H" indicates Halogen free parts, ex. SFM61-T7B-H.

Mechanical data

- Epoxy:UL94-V0 rated flame retardant
- Case : Molded plastic, TO-277B
- Terminals: Plated terminals, solderable per MIL-STD-750, Method 2026
- Polarity : Indicated by cathode band
- Mounting Position : Any
- Weight:0.092 grams(approx.)

Package outline



Maximum ratings and electrical characteristics (At $T_A=25^\circ\text{C}$ unless otherwise noted)

Rating at 25°C ambient temperature unless otherwise specified.

Single phase half-wave 60Hz, resistive or inductive load, for capacitive load current derate by 20%.

Parameter	Symbol	SFM61 -T7B	SFM62 -T7B	SFM63 -T7B	SFM64 -T7B	SFM65 -T7B	SFM66 -T7B	SFM68 -T7B	Unit
Maximum repetitive peak reverse voltage	V _{RRM}	50	100	150	200	300	400	600	V
Maximum RMS voltage	V _{RMS}	35	70	105	140	210	280	420	V
Maximum DC blocking voltage	V _{DC}	50	100	150	200	300	400	600	V
Maximum average forward rectified Current at T _L =100°C	I _(AV)	6.0							A
Peak forward surge current 8.3ms single half sinewave superimposed on rated load (JEDEC Method)	I _{FSM}	150.0							A
Maximum instantaneous forward voltage per diode at 6.0A	V _F	0.95				1.3		1.7	V
Maximum DC reverse current T _A =25°C	I _R	2.0							μA
At rated DC blocking voltage T _A =125°C		200							
Maximum reverse recovery time (Note 1)	t _{rr}	35							ns
Typical junction capacitance (Note 2)	C _J	82.0							pF
Typical thermal resistance Junction to ambient	R _{θJA}	60.0							°C/W
Operating junction temperature range	T _J	+150							°C
Storage temperature range	T _{STG}	-55 to +150							°C

Note : 1. Reverse recovery time test condition : $I_F=0.5\text{A}$, $I_R=1.0\text{A}$, $I_{rr}=0.25\text{A}$.

2. Measured at 1MHz and applied reverse voltage of 4.0V D.C.

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Rating and characteristic curves

FIG. 1- DERATING CURVE OUTPUT RECTIFIED CURRENT

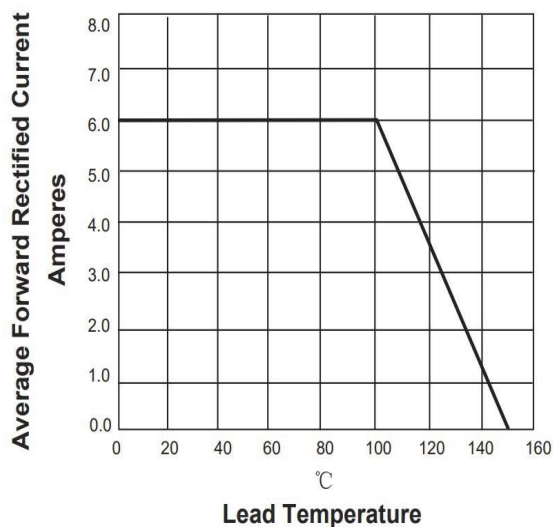


FIG. 2-MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT PER LEG

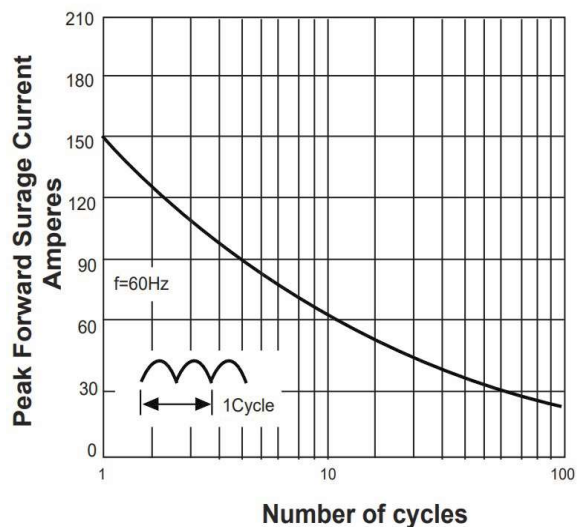


FIG. 3-TYPICAL FORWARD VOLTAGE CHARACTERISTICS

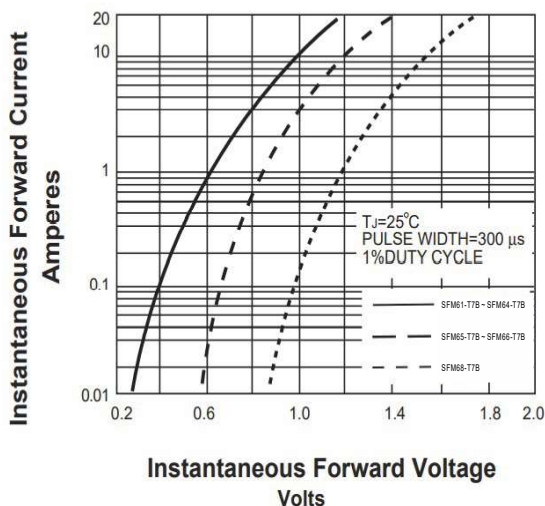
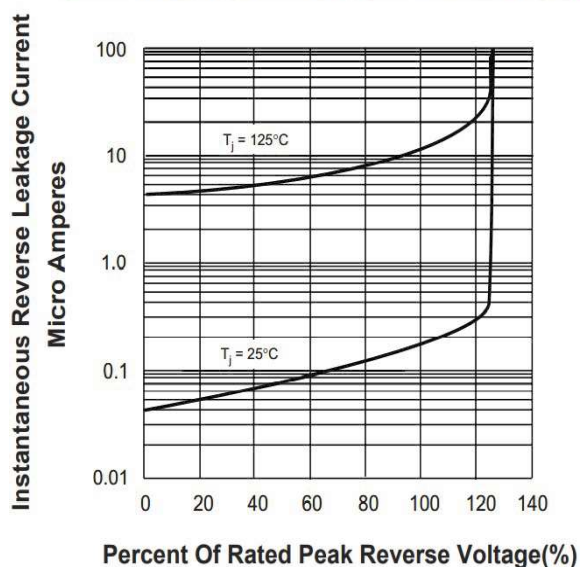
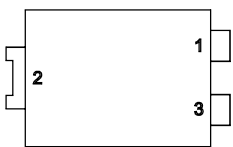
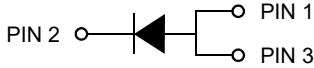


FIG. 4-TYPICAL REVERSE LEAKAGE CHARACTERISTICS



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Pinning information

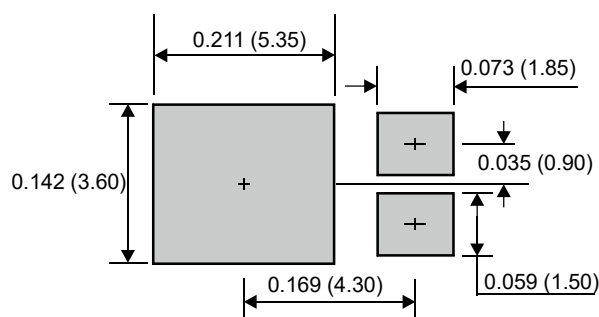
Pin	Simplified outline	Symbol
PIN 1 Anode PIN 3 Anode PIN 2 Cathode		

Marking

Type Number	Marking code
SFM61-T7B	ES6A
SFM62-T7B	ES6B
SFM63-T7B	ES6C
SFM64-T7B	ES6D
SFM65-T7B	ES6F
SFM66-T7B	ES6G
SFM68-T7B	ES6J

Suggested solder pad layout

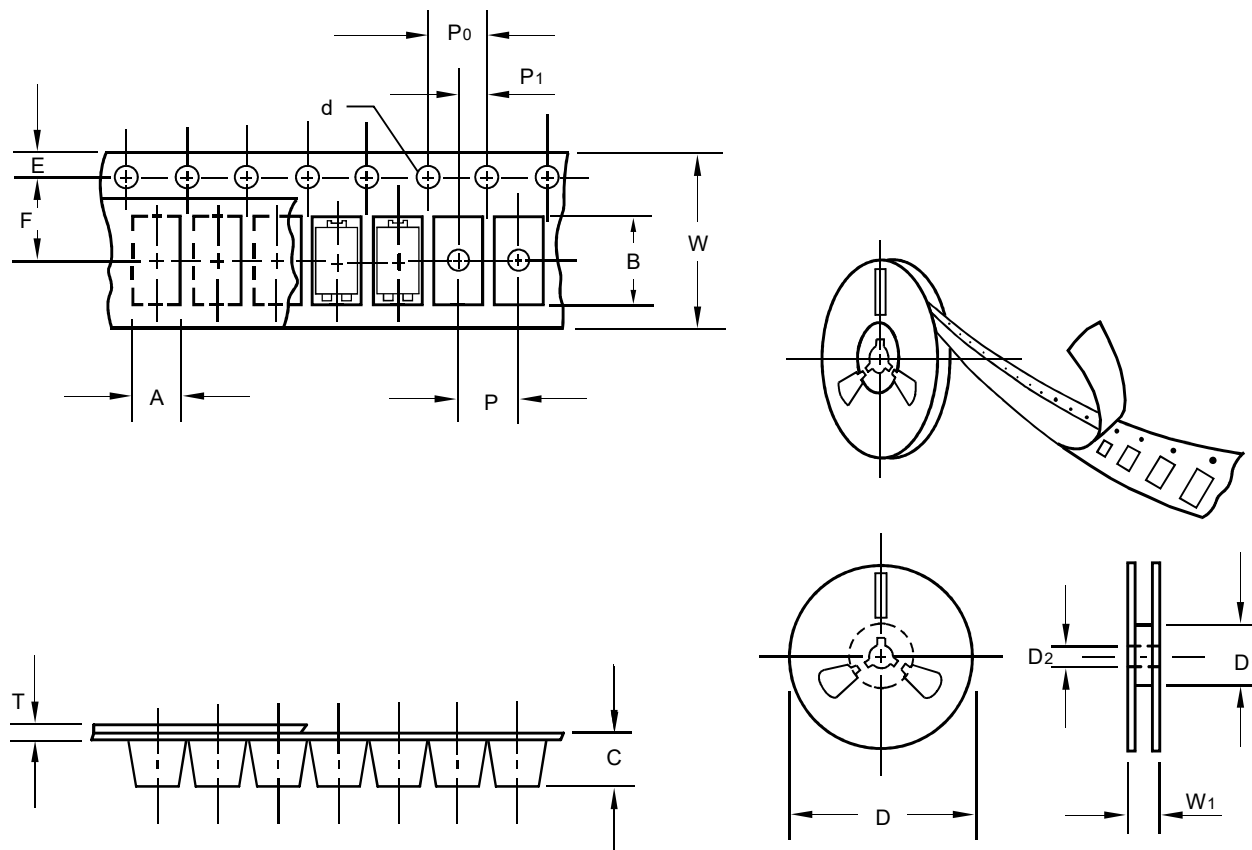
TO-277B



Dimensions in inches and (millimeters)

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Packing information



unit:mm

Item	Symbol	Tolerance	TO-277B
Carrier width	A	0.1	4.40
Carrier length	B	0.1	6.90
Carrier depth	C	0.1	1.30
Sprocket hole	d	0.1	1.55
13" Reel outside diameter	D	2.0	330.00
13" Reel inner diameter	D ₁	min	50.00
7" Reel outside diameter	D	2.0	178.00
7" Reel inner diameter	D ₁	min	62.00
Feed hole diameter	D ₂	0.5	13.00
Sprocket hole position	E	0.1	1.75
Punch hole position	F	0.1	7.50
Punch hole pitch	P	0.1	8.00
Sprocket hole pitch	P ₀	0.1	4.00
Embossment center	P ₁	0.1	2.00
Overall tape thickness	T	0.1	0.25
Tape width	W	0.3	12.00
Reel width	W ₁	1.0	14.00

Note: Devices are packed in accordance with EIA standard RS-481-A and specifications listed above.

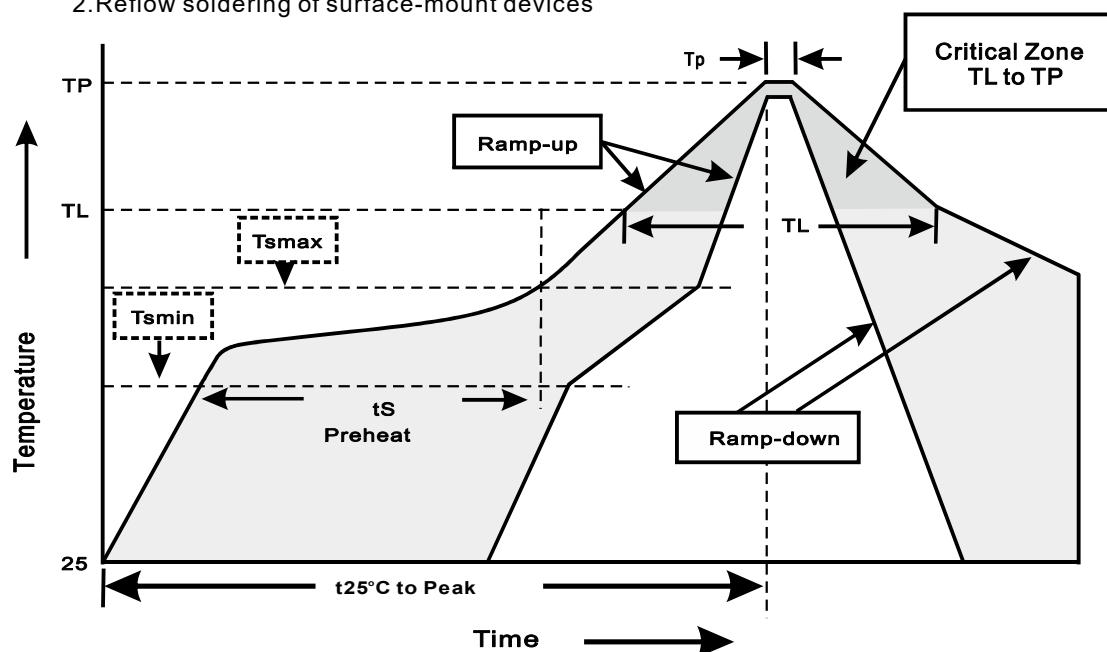
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Reel packing

PACKAGE	REEL SIZE	REEL (pcs)	COMPONENT SPACING (m/m)	BOX (pcs)	INNER BOX (m/m)	REEL DIA, (m/m)	CARTON SIZE (m/m)	CARTON (pcs)	APPROX. GROSS WEIGHT (kg)
TO-277B	13"	5,000	8.0	10,000	337*337*37	330	350*330*360	80,000	18.0

Suggested thermal profiles for soldering processes

- 1.Storage environment: Temperature=5°C~40°C Humidity=55%±25%
- 2.Reflow soldering of surface-mount devices



3.Reflow soldering

Profile Feature	Soldering Condition
Average ramp-up rate(T _L to T _P)	<3°C/sec
Preheat -Temperature Min(T _{min}) -Temperature Max(T _{max}) -Time(min to max)(t _s)	150°C 200°C 60~120sec
T _{max} to T _L -Ramp-upRate	<3°C/sec
Time maintained above: -Temperature(T _L) -Time(t _L)	217°C 60~260sec
Peak Temperature(T _P)	255°C-0/+5°C
Time within 5°C of actual Peak Temperature(t _P)	10~30sec
Ramp-down Rate	<3°C/sec
Time 25°C to Peak Temperature	<6minutes

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High reliability test capabilities

Item Test	Conditions	Reference
1. Solder Resistance	at $260\pm5^{\circ}\text{C}$ for $10\pm2\text{sec.}$ immerse body into solder $1/16''\pm1/32''$	MIL-STD-750D METHOD-2031
2. Solderability	at $245\pm5^{\circ}\text{C}$ for 5 sec.	MIL-STD-202F METHOD-208
3. High Temperature Reverse Bias	$V_R=80\%$ rate at $T_J=150^{\circ}\text{C}$ for 168 hrs.	MIL-STD-750D METHOD-1038
4. Forward Operation Life	Rated average rectifier current at $T_A=25^{\circ}\text{C}$ for 500hrs.	MIL-STD-750D METHOD-1027
5. Intermittent Operation Life	$T_A = 25^{\circ}\text{C}$, $I_F = I_O$ On state: power on for 5 min. off state: power off for 5 min. on and off for 500 cycles.	MIL-STD-750D METHOD-1036
6. Pressure Cooker	$15P_{SIG}$ at $T_A=121^{\circ}\text{C}$ for 4 hrs.	JESD22-A102
7. Temperature Cycling	-55°C to $+125^{\circ}\text{C}$ dwelled for 30 min. and transferred for 5min. total 10 cycles.	MIL-STD-750D METHOD-1051
8. Forward Surge	8.3ms single half sine-wave , one surge.	MIL-STD-750D METHOD-4066-2
9. Humidity	at $T_A=85^{\circ}\text{C}$, RH=85% for 1000hrs.	MIL-STD-750D METHOD-1021
10. High Temperature Storage Life	at 150°C for 1000 hrs.	MIL-STD-750D METHOD-1031